

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6822316".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 17:57
L2	33	("3636619" "3962052" "4348253" "4416054" "4419182" "4808273" "4930216" "4954875" "4978639" "4984358" "5037782" "5148265" "5148266" "5229647" "5252842" "5258330" "5284796" "5313366" "5424245" "5426072" "5532612" "5548091" "5578526" "5599744" "5661087" "5682062" "5861662" "5898215" "5952712" "5986339" "6005292" "6168969" "6400172").PN. OR ("6822316"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L3	82	bare with wafer with via	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L4	15	("3761782" "3947840" "4499655" "5229647" "5378927" "5406125" "5455445" "5510655" "5528080" "5552338" "5552633" "5608264" "5623160" "5675180" "5682062").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L5	1	"5973,396".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L6	1	"5973396".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L7	52	("3761782" "3947840" "4499655" "4764846" "4972248" "4983533" "5128831" "5229647" "5266833" "5298767" "5378927" "5386142" "5406125" "5434745" "5455445" "5468997" "5481133" "5481134" "5510655" "5528080" "5552633" "5608264" "5623160" "5675180" "5682062").PN. OR ("5973396"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L9	27	("5973396").URPN.	USPAT	OR	ON	2005/11/08 17:57
L10	863	wafer with via with pad	USPAT	OR	ON	2005/11/08 17:57
L11	0	L10 and pristine adj (substrate wafer)	USPAT	OR	ON	2005/11/08 18:03
L12	28	pristine adj (substrate wafer)	USPAT	OR	ON	2005/11/08 17:57
L13	822	unprocessed adj (substrate wafer)	USPAT	OR	ON	2005/11/08 18:02
L14	22	unprocessed adj (substrate wafer) with via	USPAT	OR	ON	2005/11/08 17:57

L15	34	("20010005046" "3636619" "3962052" "4348253" "4416054" "4808273" "4930216" "4978639" "4984358" "5037782" "5148265" "5148266" "5229647" "5252842" "5258330" "5284796" "5313366" "5424245" "5532612" "5548091" "5578526" "5661087" "5682062" "5861662" "5898215" "5952712" "5986339" "6005292" "6030855" "6110825" "6168969" "6198168" "6268660" "6495454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L16	29	unprocessed near2 (substrate wafer) with via	USPAT	OR	ON	2005/11/08 18:00
L17	7	L16 not L14	USPAT	OR	ON	2005/11/08 17:57
L18	49	unprocessed near2 (substrate wafer) with via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 18:04
L19	20	L18 not L16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 17:57
L20	1	virgin near2 (substrate wafer) with via	USPAT	OR	ON	2005/11/08 17:57
L21	1197	(substrate wafer) with un\$2processed	USPAT	OR	ON	2005/11/08 17:57
L22	34	(substrate wafer) with un\$2processed with via	USPAT	OR	ON	2005/11/08 17:57
L23	5	L22 not L16	USPAT	OR	ON	2005/11/08 17:57
L24	57	(substrate wafer) with un\$2processed with via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 17:57
L25	28	L24 not L16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 17:57

L26	33	("3636619" "3962052" "4348253" "4416054" "4419182" "4808273" "4930216" "4954875" "4978639" "4984358" "5037782" "5148265" "5148266" "5229647" "5252842" "5258330" "5284796" "5313366" "5424245" "5426072" "5532612" "5548091" "5578526" "5599744" "5661087" "5682062" "5861662" "5898215" "5952712" "5986339" "6005292" "6168969" "6400172").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/08 17:57
L27	2	"6822316".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 17:59
L29	414	(257/621).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:02
L30	2376	(257/774).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:01
L31	780	(257/776).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:01
L32	1773	(257/690).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:01
L33	256	(257/699).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:01
L34	1686	(257/700).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:01

L35	330	(257/708).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:01
L36	2628	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:01
L37	613	(257/618).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:02
L38	1648	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/08 18:02
L39	10992	29 30 31 32 33 34 35 36 37 38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 18:02
L40	8	39 and unprocessed near2 (substrate wafer)	USPAT	OR	ON	2005/11/08 18:02
L41	9	39 and unprocessed with (substrate wafer)	USPAT	OR	ON	2005/11/08 18:03
L42	12	39 and unprocessed same(substrate wafer)	USPAT	OR	ON	2005/11/08 18:03
L43	427	39 and (pristine virgin new unprocessed) same(substrate wafer)	USPAT	OR	ON	2005/11/08 18:13
L44	224	39 and (pristine virgin new unprocessed) with (substrate wafer)	USPAT	OR	ON	2005/11/08 18:04
L45	302	39 and (pristine virgin new unprocessed) with (substrate wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/11/08 18:04
L46	138	45 and (substrate wafer) with via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 18:04

L47	199	45 and (substrate wafer) with (hole via throughole though cavity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/08 18:05
L48	476	((pristine virgin new unprocessed) and (substrate wafer)and (hole via throughole though cavity)).clm.	US-PGPUB	OR	ON	2005/11/08 18:15
L51	101	((pristine virgin new unprocessed) and (substrate wafer)and (hole via throughole though cavity) and (pad interconnect\$3 I/O)).clm.	US-PGPUB	OR	ON	2005/11/08 18:15